

In the Title

Please amend the title by removing the words "PROCESS TECHNOLOGY". A clean version of the title is now

INSULATED BOND WIRE ASSEMBLY FOR INTEGRATED CIRCUITS

In the Claims

Please cancel claims 4, 13, and 19-27 and amend the claims in the manner indicated. A clean version of all pending claims after the amendment is shown on the following pages. A marked-up version of the amended claims is shown in Appendix A at the end of this response.

Clean version of all pending claims

1. (Amended once) An apparatus comprising:

a bond wire;

an insulating material coating said bond wire, the insulating material having a thickness in the range of approximately 0.2 micrometers to approximately 0.6 micrometers; and

a first end of said bond wire connected to a bond pad.

2. (Amended twice) The apparatus of claim 1 wherein said bond wire material is selected from a group consisting of gold, silver, aluminum, and copper.

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3. The insulated bond wire of claim 1 wherein said insulating material is comprised of a polymer.

5. (Amended once) The apparatus of claim 1 wherein said bond wire is connected to said bond pad through an ultrasonic bond.

6. (Amended once) The apparatus of claim 1 further comprising said bond pad connected to an integrated circuit.

7. (Amended once) The apparatus of claim 1 further comprising said bond pad connected to a substrate.

8. (Amended twice) An integrated circuit comprising:
a first bond wire;
an insulating material coating said first bond wire;
a first end of said first bond wire connected to a bond pad by ultrasonic bonding without previously removing the insulating material from the first end; and
a second bond wire crossing said first bond wire.

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9. (Amended once) The integrated circuit of claim 8 further comprising an insulating material coating said second bond wire.

10. The pair of bond wires of claim 8 wherein said first bond wire touches said second bond wire.

11. (Amended once) An integrated circuit assembly comprising:

an integrated circuit;

a substrate;

a bond wire connected to said integrated circuit and said substrate; and

a polymer insulating material coating said bond wire.

12. (Amended once) The integrated circuit assembly of claim 11 wherein said substrate is selected from a group consisting of printable circuit boards, aluminum lead frames, and fine pitch ball grid arrays.

14. (Amended once) The integrated circuit assembly of claim 11 wherein said bond wire material is selected from a group consisting of gold, silver, aluminum, and copper.

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15. (Amended once) An integrated circuit assembly comprising:

a first integrated circuit;

a second integrated circuit;

a bond wire connected to said first integrated circuit and said second integrated circuit; and

an insulating material coating said bond wire to a thickness of between about .2 micrometers and about .6 micrometers.

16. (Amended twice) The integrated circuit assembly of claim 15 wherein said second integrated circuit is selected from a group consisting of printable circuit boards, aluminum lead frames, and fine pitch ball grid arrays.

17. The integrated circuit assembly of claim 15 wherein said insulating material is comprised of a polymer.

18. (Amended once) The integrated circuit assembly of claim 15 wherein said bond wire material is selected from a group consisting of gold, silver, aluminum, and copper.